MA27V03

Silicon epitaxial planar type

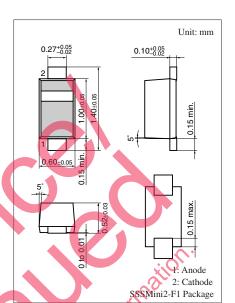
For VCO

Features

- \bullet Good linearity and large capacitance-ratio in C_D V_R relation
- \bullet Small series resistance $r_{\rm D}$
- SSS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	6	V
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C



Marking Symbol: 3

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

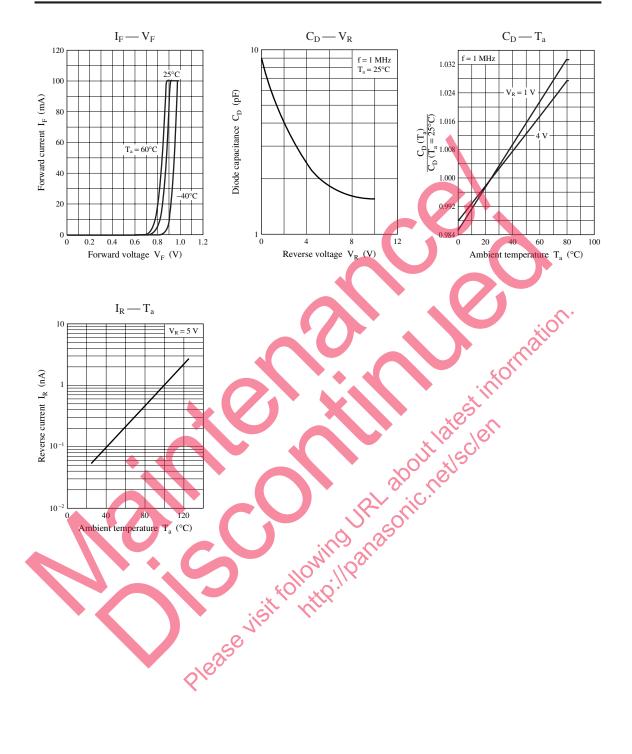
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$								
Parameter	Symbol	Conditions	Min	Тур	Max	Unit		
Reverse current	I _R	$V_R = 5 V$			10	nA		
Diode capacitance	C _{D(1V)}	$V_R = 1 V, f = 1 MHz$	5.20		5.80	pF		
	C _{D(4V)}	$V_R = 4$ V, $T = 1$, MHz	2.10		2.58			
Capacitance ratio	C _{D(1V)} /C _{D(4V)}		2.1		2.6			
Series resistance *	r _D	$V_{R} = 4 V_{*} f = 470 \text{ MHz}$			0.3	Ω		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 470 MHz.

3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER





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